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August 2024

# FQPF9N25C / FQPF9N25CT N-Channel QFET® MOSFET

250 V, 8.8 A, 430 mΩ

### **Features**

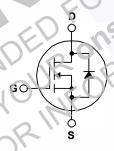
- 8.8 A, 250 V,  $R_{DS(on)}$  = 430 m $\Omega$  (Max.) @  $V_{GS}$  = 10 V,  $I_D$  = 4.4 A
- Low Gate Charge (Typ. 26.5 nC)
- Low Crss (Typ. 45.5 pF)
- · 100% Avalanche Tested

### **Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC convertors, switch mode power supplies, DC-AC convertors for uninterrupted power supplies and motor controls.





### MOSFET Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter		FQPF9N25C / FQPF9N25CT	Unit	
V <sub>DSS</sub>	Drain to Source Voltage	C		250	V
I <sub>D</sub>	Drain Current	· Continuous (T <sub>C</sub> = 25°C)		8.8 *	Α
	Drain Guirent	- Continuous (T <sub>C</sub> = 100°C)		5.6 *	Α
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	35.2 *	Α
V <sub>GSS</sub>	Gate to Source Voltage		± 30	V	
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		(Note 2)	285	mJ
I <sub>AR</sub>	Avalanche Current (r		(Note 1)	8.8	Α
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		(Note 1)	7.4	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		5.5	V/ns	
$P_{D}$	Power Dissipation	(T <sub>C</sub> = 25°C)		38	W
	Fower Dissipation	- Derate Above 25°C		0.3	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range			-55 to +150	°C
T <sub>L</sub>	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300	°C	

<sup>\*</sup>Drain current limited by maximum junction temperature

### **Thermal Characteristics**

Symbol	Parameter	FQPF9N25C / FQPF9N25CT	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	3.29	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	C/VV

## **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FQPF9N25C	FQPF9N25C	TO-220F	Tube	N/A	50 units
FQPF9N25CT	FQPF9N25CT	TO-220F	Tube	N/A	50 units

### **Electrical Characteristics** T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Cha	racteristics					
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	250			V
$\Delta BV_{DSS}$ / $\Delta T_{J}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, Referenced to 25°C		0.30		V/°C
1	Zara Cata Valtana Dusin Comment	V <sub>DS</sub> = 250 V, V <sub>GS</sub> = 0 V		-	10	μА
IDSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 200 V, T <sub>C</sub> = 125°C	-	1	100	μA
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V	-		100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30 V, V <sub>DS</sub> = 0 V			-100	nA
On Cha	racteristics				U.	
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0	17/	4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V <sub>1</sub> I <sub>D</sub> = 4.4 A	OP	0.35	0.43	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 4.4 A	Y	7.0	.6	S
Dynami	ic Characteristics	EL	OUS	NA		
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$	2 /	545	710	pF
Coss	Output Capacitance	f = 1.0 MHz		115	150	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	MALLO		45.5	60	pF
Switchi	ng Characteristics	COM CT 1011	7,			
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 125 V, I <sub>D</sub> = 8.3 A,		15	40	ns
t <sub>r</sub>	Turri-On Rise Time	$V_{\rm CS} = 10 \text{ V}, R_{\rm G} = 25 \Omega$		85	180	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			90	190	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4	·)	65	140	ns
Qg	Total Gate Charge	$V_{DS} = 200 \text{ V}, I_{D} = 8.8 \text{ A},$	/	26.5	35	nC
Qgs	Gate Source Charge	V <sub>GS</sub> = 10 V		3.5		nC
$Q_{gd}$	Gate-Drain Charge	(Note 4		13.5		nC
Drain-S	ource Diode Characteristics and	l Maximum Ratings				
Is	Maximum Continuous Drain-Source Diode				8.8	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode For	rward Current			35.2	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 8.8 A			1.5	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 8.8 A,		218		ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> / dt = 100 A/μs		1.58		μС

#### Notes

<sup>1.</sup> Repetitive rating : pulse-width limited by maximum junction temperature.

<sup>2.</sup> L = 5.9 mH, I<sub>AS</sub> = 8.8 A, V<sub>DD</sub> = 50 V, R<sub>G</sub> = 25  $\Omega$ , starting T<sub>J</sub> = 25°C.

<sup>3.</sup>  $I_{SD} \le 8.8$  A, di/dt  $\le 300$  A/ $\mu$ s,  $V_{DD} \le BV_{DSS_3}$  starting  $T_J$  = 25°C.

<sup>4.</sup> Essentially independent of operating temperature.

### **Typical Characteristics**

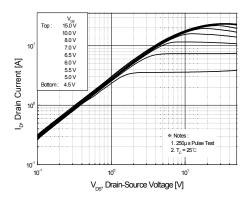


Figure 1. On-Region Characteristics

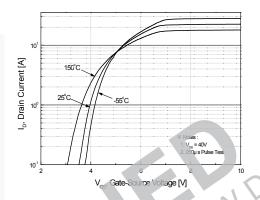


Figure 2. Transfer Characteristics

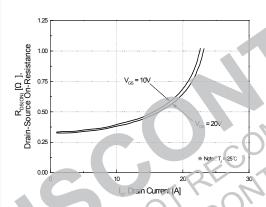


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

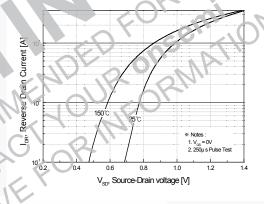


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

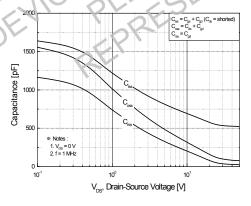


Figure 5. Capacitance Characteristics

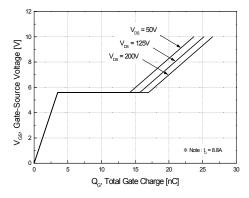
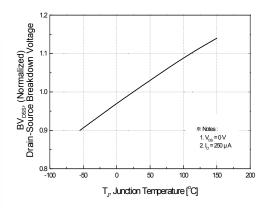


Figure 6. Gate Charge Characteristics

### Typical Characteristics (Continued)



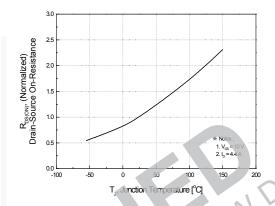
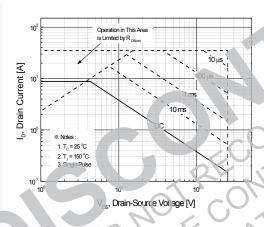


Figure 7. Breakdown Voltage Variation vs Temperature





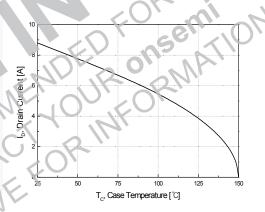


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs Case Temperature

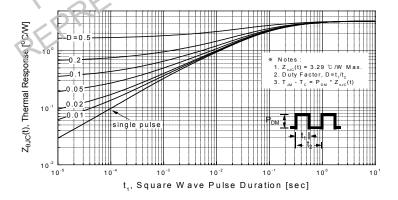


Figure 11. Transient Thermal Response Curve

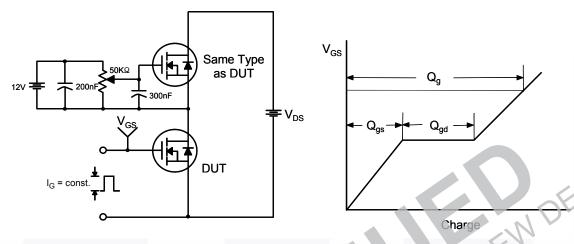


Figure 12. Gate Charge Test Circuit & Waveform

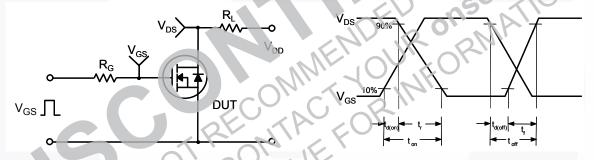


Figure 13. Resistive Switching Test Circuit & Waveforms

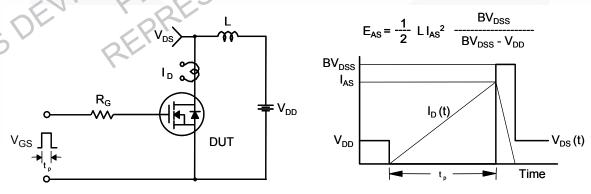


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

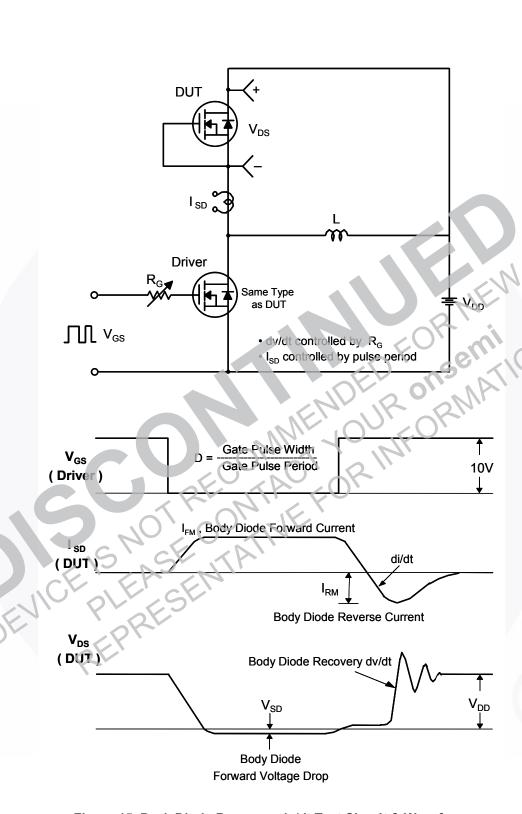


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

### **Mechanical Dimensions**

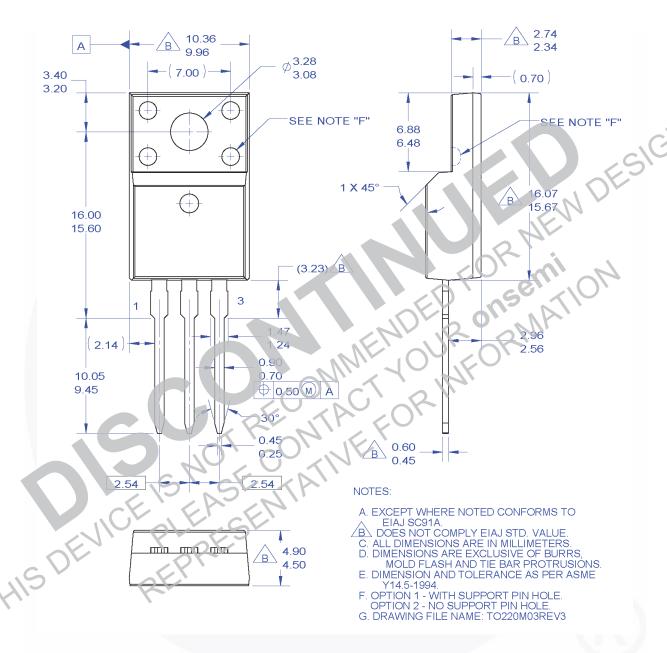


Figure 16. TO220, Molded, 3-Lead, Full Pack, EIAJ SC91, Straight Lead

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